

In the Claims:

1 **1.** (Original) An electronic device (1)
2 - with a base plate (2),
3 - with an electronics housing (3) which is connected to
4 the base plate (2), with at least one bond contact
5 bearer (5),
6 characterised in that the bond contact bearer (5) is
7 supported on the base plate (2) by a supporting body (6) in
8 such a manner that the supporting body (6) exerts a
9 pretension force onto the bond contact bearer (5).

1 **2.** (Original) An electronic device according to claim 1,
2 characterised in that a projection of the supporting body
3 (6) above the base plate (2) is greater than the distance
4 between the bond contact bearer (5) and the base plate (2).

Claims 3 and 4 (Canceled).

1 **5.** (Original) A procedure for bonding an electronic device (1)
2 with the following procedural stages:
3 - provision of a base plate (2),
4 - connection of an electronics housing (3) via a
5 supporting body (6) with the base plate (2) in such a

6 manner that the supporting body (6) exerts a
7 pretension force onto the bond contact bearer (5),
8 - creation of a bond connection between the bond contact
9 bearer (5) of the electronics housing (3) and an
10 additional bond contact bearer.

1 6. (New) An electronic device according to claim 1,
2 characterized in that the supporting body (6) represents a
3 separate component from the base plate (2), which is
4 mechanically connected to the electronics housing (3).

1 7. (New) An electronic device according to claim 1,
2 characterized in that the supporting body (6) is designed
3 as a projecting ring or as a plurality of projecting
4 individual segments.

[REMARKS FOLLOW ON NEXT PAGE]